



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20150420000
Datasheet update for TMP75/TMP175
Information Only**

Date: 4/22/2015
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150420000
Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP75AID	null
TMP75AIDGKT	null
TMP175AID	null
TMP175AIDGKT	null
TMP75AIDR	null
TMP75AIDGKR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150420000	PCN Date:	04/22/2014
Title:	Datasheet update for TMP75/TMP175		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



TMP175, TMP75

SBOS288K – JANUARY 2004 – REVISED APRIL 2015

www.ti.com

Changes from Revision J (December 2007) to Revision K

Page

- Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. 1
- Updated parameters in the Timing Requirements table. 6

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP75/TMP175	SBOS288J	SBOS288K

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/tmp175>

<http://www.ti.com/product/tmp75>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP175AID	TMP175AIDGKTG4	TMP75AIDG4	TMP75AIDGKTG4	
TMP175AIDG4	TMP175AIDR	TMP75AIDGKR	TMP75AIDR	
TMP175AIDGKR	TMP175AIDRG4	TMP75AIDGKRG4	TMP75AIDRG4	
TMP175AIDGKT	TMP75AID	TMP75AIDGKT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com